

LM431 Adjustable Precision Zener Shunt Regulator

Check for Samples: LM431

FEATURES

- Average Temperature Coefficient 50 ppm/°C
- Temperature Compensated for Operation Over the Full Temperature Range
- Programmable Output Voltage
- Fast Turn-On Response
- Low Output Noise

DESCRIPTION

The LM431 is a 3-terminal adjustable shunt regulator with ensured temperature stability over the entire temperature range of operation. The output voltage may be set at any level greater than 2.5V (V_{REF}) up to 36V merely by selecting two external resistors that act as a voltage divided network. Due to the sharp turn-on characteristics this device is an excellent replacement for many zener diode applications.

Connection Diagram

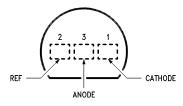


Figure 1. TO-92: Plastic Package Top View

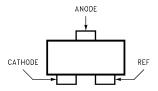


Figure 2. SOT-23: 3-Lead Small Outline Top View

A. Note: NC = Not internally connected.

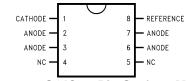
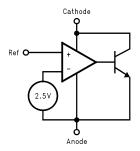


Figure 3. SOIC: 8-Pin Surface Mount Top view

Symbol and Functional Diagrams



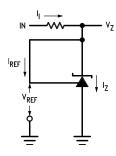


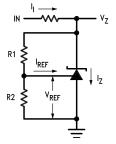
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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



DC Test Circuits





Note: $V_Z = V_{REF} (1 + R1/R2) + I_{REF} R1$

Figure 4. Test Circuit for $V_Z = V_{REF}$



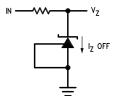


Figure 6. Test Circuit for Off-State Current



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)(2)

Storage Temperature Range		−65°C to +150°C
Operating Temperature Range	Industrial (LM431xI)	−40°C to +85°C
	Commercial (LM431xC)	0°C to +70°C
Soldering Information	Infrared or Convection (20 sec.)	235°C
	Wave Soldering (10 sec.)	260°C (lead temp.)
Cathode Voltage		37V
Continuous Cathode Current		−10 mA to +150 mA
Reference Voltage		-0.5V
Reference Input Current		10 mA
Internal Power Dissipation (3)(4)	TO-92 Package	0.78W
	SOIC Package	0.81W
	SOT-23 Package	0.28W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Electrical specifications do not apply when operating the device beyond its rated operating conditions.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) $T_{J \text{ Max}} = 150^{\circ} \text{C}.$
- (4) Ratings apply to ambient temperature at 25°C. Above this temperature, derate the TO-92 at 6.2 mW/°C, the SOIC at 6.5 mW/°C, the SOT-23 at 2.2 mW/°C.

Operating Conditions

	Min	Max
Cathode Voltage	V_{REF}	37V
Cathode Current	1.0 mA	100 mA

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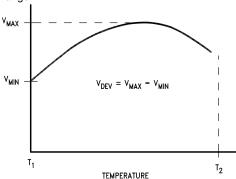


LM431 Electrical Characteristics

T_A = 25°C unless otherwise specified

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V _{REF}	Reference Voltage	V _Z = V _{REF} , I _I = 10 mA LM431A (<i>Figure 4</i>)	2.440	2.495	2.550	V
		$V_Z = V_{REF}$, $I_I = 10 \text{ mA}$ LM431B (<i>Figure 4</i>)	2.470	2.495	2.520	V
		$V_Z = V_{REF}$, $I_I = 10 \text{ mA}$ LM431C (Figure 4)	2.485	2.500	2.510	V
V_{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_I = 10 \text{ mA}$, $T_A = \text{Full Range } (\text{Figure 4})$		8.0	17	mV
$\Delta V_{REF}/\Delta V_{Z}$	Ratio of the Change in Reference Voltage	$I_Z = 10 \text{ mA}$ $V_Z \text{ from } V_{REF} \text{ to } 10V$		-1.4	-2.7	mV/V
	to the Change in Cathode Voltage	(Figure 5) V _Z from 10V to 36V		-1.0	-2.0	
I _{REF}	Reference Input Current	$R_1 = 10 \text{ k}\Omega, R_2 = \infty, I_1 = 10 \text{ mA}$ (Figure 5)		2.0	4.0	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega, R_2 = \infty, I_1 = 10 \text{ mA},$ $T_A = \text{Full Range } (Figure 5)$		0.4	1.2	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	$V_Z = V_{REF}(Figure 4)$		0.4	1.0	mA
I _{Z(OFF)}	Off-State Current	V _Z = 36V, V _{REF} = 0V (Figure 6)		0.3	1.0	μΑ
r _Z	Dynamic Output Impedance ⁽²⁾	V _Z = V _{REF} , LM431A, Frequency = 0 Hz <i>(Figure 4)</i>			0.75	Ω
		V _Z = V _{REF} , LM431B, LM431C Frequency = 0 Hz <i>(Figure 4)</i>			0.50	Ω

(1) Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range.



The average temperature coefficient of the reference input voltage, «V_{REF}, is defined as:

 $T_2 - T_1 = \text{full temperature change (0-70°C)}.$

V_{REF} can be positive or negative depending on whether the slope is positive or negative.

Example: $V_{DEV} = 8.0 \text{ mV}$, $V_{REF} = 2495 \text{ mV}$, $T_2 - T_1 = 70^{\circ}\text{C}$, slope is positive.

$$\propto V_{REF} = \frac{\left[\frac{8.0 \text{ mV}}{2495 \text{ mV}}\right]_{106}}{70^{\circ}\text{C}} = +46 \text{ ppm/°C}$$

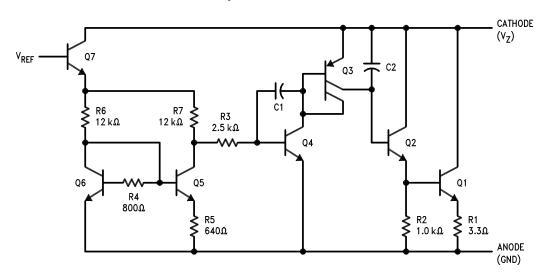
The dynamic output impedance, $r_Z,$ is defined as: $r_Z = \frac{\Delta V_Z}{\Delta I_Z}$

When the device is programmed with two external resistors, R1 and R2, (see Figure 5), the dynamic output impedance of the overall circuit, r_Z , is defined as: $r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$



Equivalent Circuit





Typical Performance Characteristics

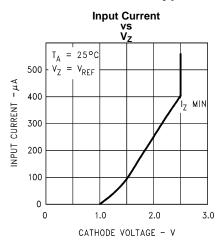
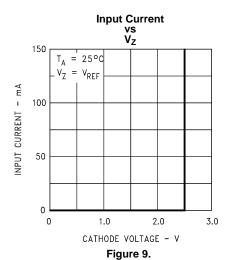
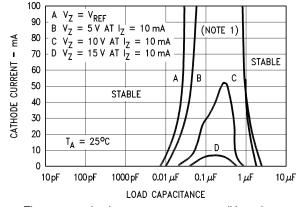


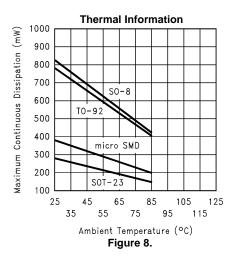
Figure 7.

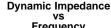


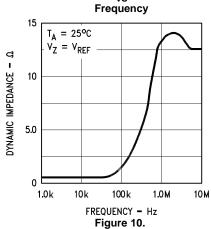
Stability Boundary Conditions



Note: The areas under the curves represent conditions that may cause the device to oscillate. For curves B, C, and D, R2 and V⁺ were adjusted to establish the initial V_Z and I_Z conditions with $C_L = 0$. V⁺ and C_L were then adjusted to determine the ranges of stability. **Figure 11.**







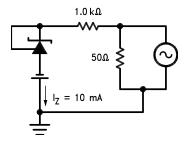
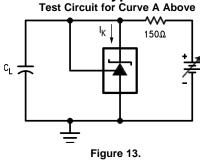
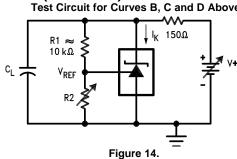


Figure 12.



Typical Performance Characteristics (continued) Test Circuit for Curve A Above Test Circuit for Curves B, C and D Above





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Typical Applications

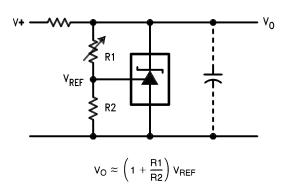


Figure 15. Shunt Regulator

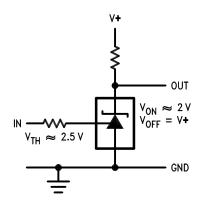


Figure 16. Single Supply Comparator with Temperature Compensated Threshold

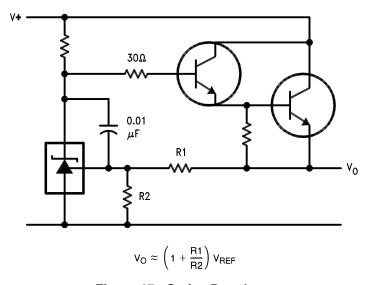


Figure 17. Series Regulator



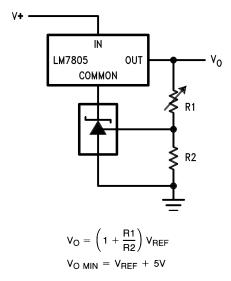


Figure 18. Output Control of a Three Terminal Fixed Regulator

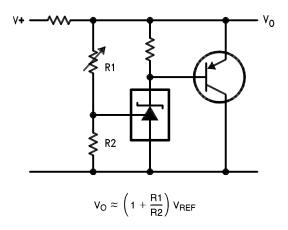


Figure 19. Higher Current Shunt Regulator

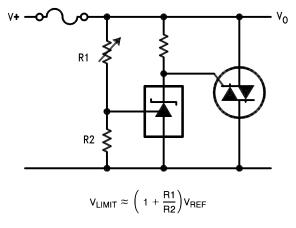
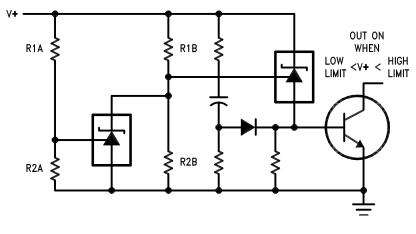


Figure 20. Crow Bar

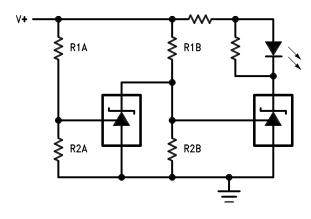
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$$\begin{split} &\text{LOW LIMIT} \approx \text{V}_{\text{REF}} \left(1 + \frac{\text{R1B}}{\text{R2B}} \right) + \text{V}_{\text{BE}} \\ &\text{HIGH LIMIT} \approx \text{V}_{\text{REF}} \left(1 + \frac{\text{R1A}}{\text{R2A}} \right) \end{split}$$

Figure 21. Over Voltage/Under Voltage Protection Circuit



$$\begin{split} & \text{LOW LIMIT} \approx V_{\text{REF}} \left(1 + \frac{\text{R1B}}{\text{R2B}}\right) & \text{LED ON WHEN} \\ & \text{LOW LIMIT} < V^+ < \text{HIGH LIMIT} \\ & \text{HIGH LIMIT} \approx V_{\text{REF}} \left(1 + \frac{\text{R1A}}{\text{R2A}}\right) \end{split}$$

Figure 22. Voltage Monitor



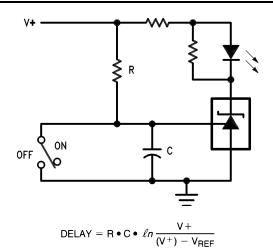


Figure 23. Delay Timer

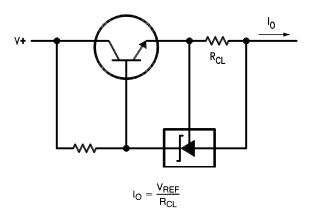


Figure 24. Current Limiter or Current Source

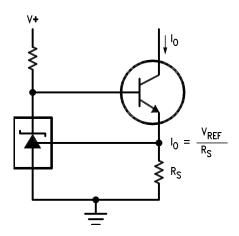


Figure 25. Constant Current Sink

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REVISION HISTORY

Cł	hanges from Revision F (April 2013) to Revision G	Pag	ge
•	Changed layout of National Data Sheet to TI format		10





11-Dec-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM431ACM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	LM431 ACM	
LM431ACM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM431 ACM	Samples
LM431ACM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1F	Samples
LM431ACM3X	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	N1F	
LM431ACM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1F	Samples
LM431ACMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM431 ACM	Samples
LM431ACZ/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM431 ACZ	Samples
LM431ACZ/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM431 ACZ	Samples
LM431ACZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU	N / A for Pkg Type	-40 to 85	LM431 ACZ	Samples
LM431AIM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	LM431 AIM	
LM431AIM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM431 AIM	Samples
LM431AIM3	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	N1E	
LM431AIM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1E	Samples
LM431AIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1E	Samples
LM431AIMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM -40 to		LM431 AIM	Samples
LM431AIZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM431 AIZ	Samples
LM431AIZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	LM431 AIZ	Samples
LM431BCM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 BCM	Samples



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Orderable Device	Status	Package Type	_	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sampl
LMADADOMO	(1)	COT 00	Drawing		Qty	(2)	(6)	(3)	40 to 05	(4/5)	
LM431BCM3	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	N1D	
LM431BCM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1D	Sampl
LM431BCM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1D	Samp
LM431BCMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 BCM	Samp
LM431BCZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU	N / A for Pkg Type	-40 to 85	LM431 BCZ	Samp
LM431BIM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	431 BIM	
LM431BIM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 BIM	Samp
LM431BIM3	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	N1C	
LM431BIM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1C	Sam
LM431BIM3X	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	N1C	
LM431BIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1C	Samj
LM431BIMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 BIM	Sam
LM431CCM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 CCM	Sam
LM431CCM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1B	Sam
LM431CCM3X	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	N1B	
LM431CCM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1B	Sam
LM431CCZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU	N / A for Pkg Type	-40 to 85	LM431 CCZ	Sam
LM431CIM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	431 CIM	
LM431CIM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	431 CIM	Sam
LM431CIM3	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	N1A	



PACKAGE OPTION ADDENDUM

11-Dec-2014

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM431CIM3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1A	Samples
LM431CIM3X	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	N1A	
LM431CIM3X/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N1A	Samples
LM431CIZ/LFT1	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM431 CIZ	Samples
LM431CIZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	LM431 CIZ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

11-Dec-2014

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PACKAGE MATERIALS INFORMATION

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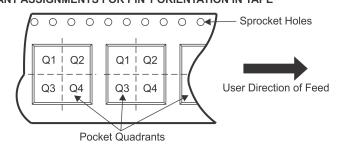
TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity AO

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



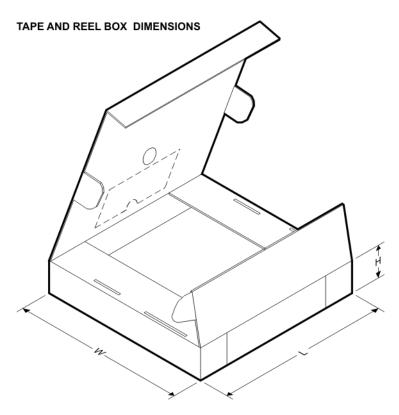
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM431ACM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431ACM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431ACM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431ACMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM431AIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431AIM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431AIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM431BCM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BCM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BCM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BCMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM431BIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BIM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431BIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM431CCM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM431CCM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431CCM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431CIM3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431CIM3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431CIM3X	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM431CIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM431ACM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431ACM3X	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431ACM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431ACMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM431AIM3	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431AIM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431AIM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM431BCM3	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431BCM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431BCM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0



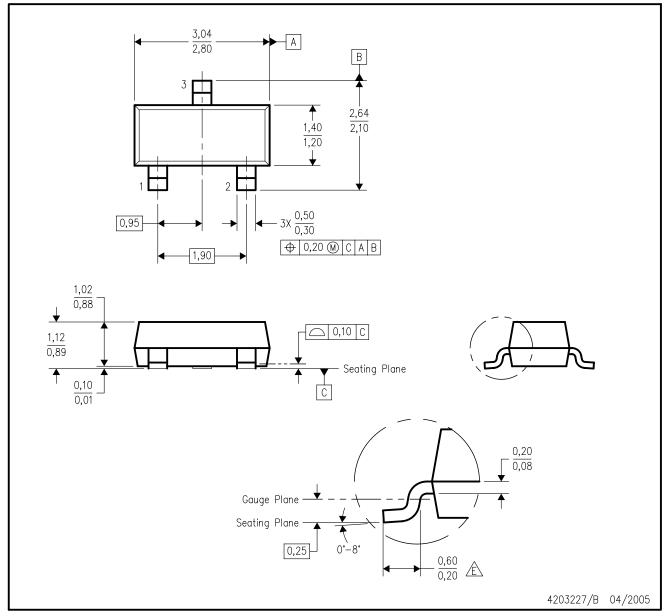
PACKAGE MATERIALS INFORMATION

www.ti.com 5-Dec-2014

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM431BCMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM431BIM3	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431BIM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431BIM3X	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431BIM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431BIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM431CCM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431CCM3X	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431CCM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431CIM3	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431CIM3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM431CIM3X	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM431CIM3X/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



D (R-PDSO-G8)

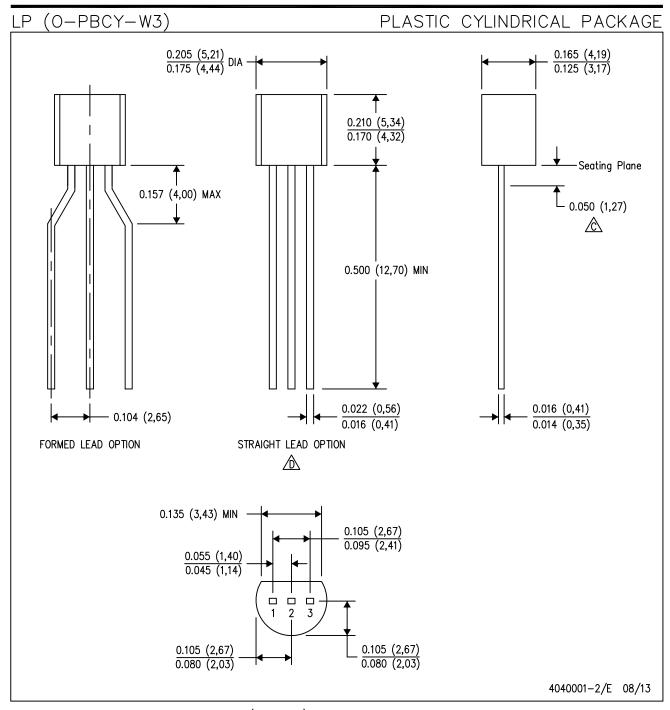
PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Lead dimensions are not controlled within this area.

Falls within JEDEC TO−226 Variation AA (TO−226 replaces TO−92).

E. Shipping Method:

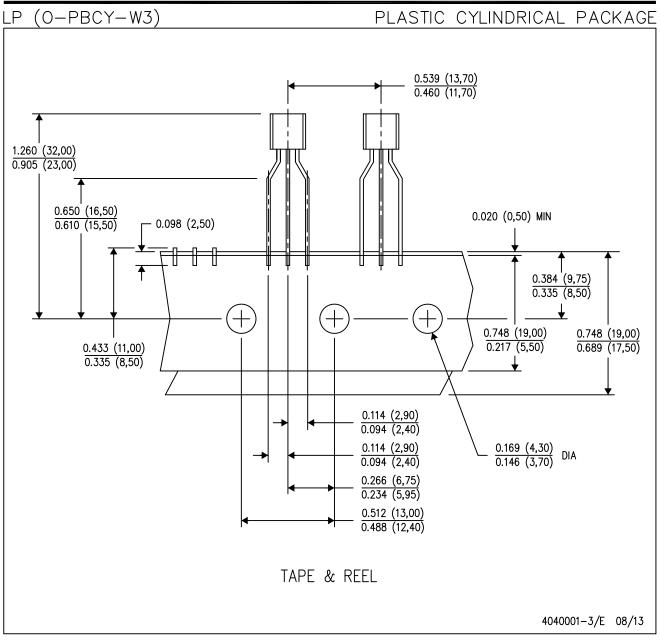
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.

Specific products can be offered in limited combinations of shipping mediums and lead options.

Consult product folder for more information on available options.





NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Tape and Reel information for the Formed Lead Option package.

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